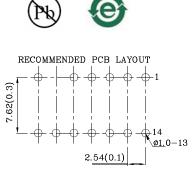


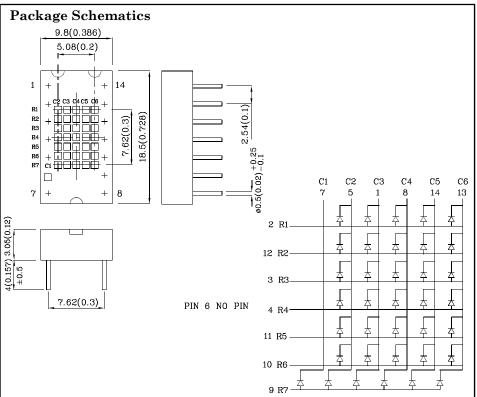
Part Number: XMUR07C

7.62mm (0.3 ") SINGLE COLOR DOT MATRIX DIS-PLAY

Features

- \bullet Low power consumption
- \bullet Robust package
- I.C. Compatible
- Optional black face provides superior color contrast
- RoHS Compliant





Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01")$ unless otherwise noted. 2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		UR (GaAsP/GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	$I_{\rm F}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	160	mA	
Power Dissipation	\mathbf{P}_{D}	75	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	$-40 \sim +85$		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

Operating Characteristics (T _A =25°C)		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	1.9	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)			uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	7* (Typ.) λP 627*		nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	617*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	f-Maximum (Typ.) △λ 45		nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (IF=10mA) ucd		Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XMUR07C	Red	GaAsP/GaP	2200 900*	5590 1790*	627*	Column Cathode

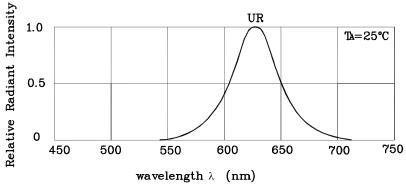
 ${\rm *Luminous\ intensity\ value\ and\ wavelength\ are\ in\ accordance\ with\ CIE127 {\rm \cdot}2007\ standards.}$

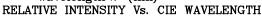
Mar 03,2014

XDSA1806 V7-X Layout: Maggie L.

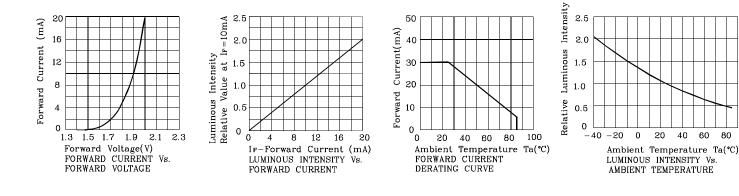


Part Number: XMUR07C 7.62mm (0.3 ") SINGLE COLOR DOT MATRIX DIS-PLAY

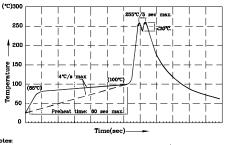




♦ UR



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



nmend pre-heat temperature of 105°C or less (as measured with a nocouple attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 280°C wave soldering temperature between 245°C \sim 255°C for 3 sec (5 sec 1. Rec the wave 2.Peak

 Peak wave soldering temperature between max).
Do not apply stress to the epoxy result.
Pixtures should not incur stress on the during soldering process.
SAC 305 solder alloy is recommended.
No more than one wave soldering pass. while the temperature is all component when mounting sin the

Remarks:

If special sorting is required (e.g. binning based on forward voltage,

0 20 40 60 80

luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

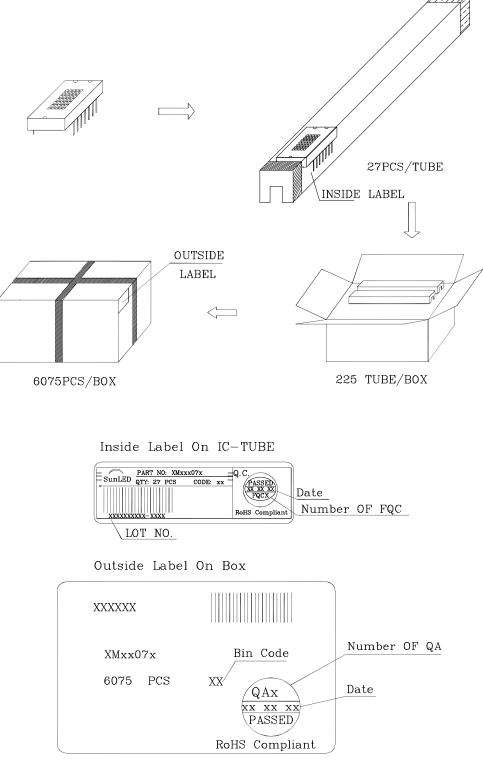
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V
- Note: Accuracy may depend on the sorting parameters.



Part Number: XMUR07C

7.62mm (0.3 ") SINGLE COLOR DOT MATRIX DIS-PLAY

PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
- consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- $6. \ Additional \ technical \ notes \ are \ available \ at \ \underline{http://www.SunLEDusa.com/TechnicalNotes.asp}$

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